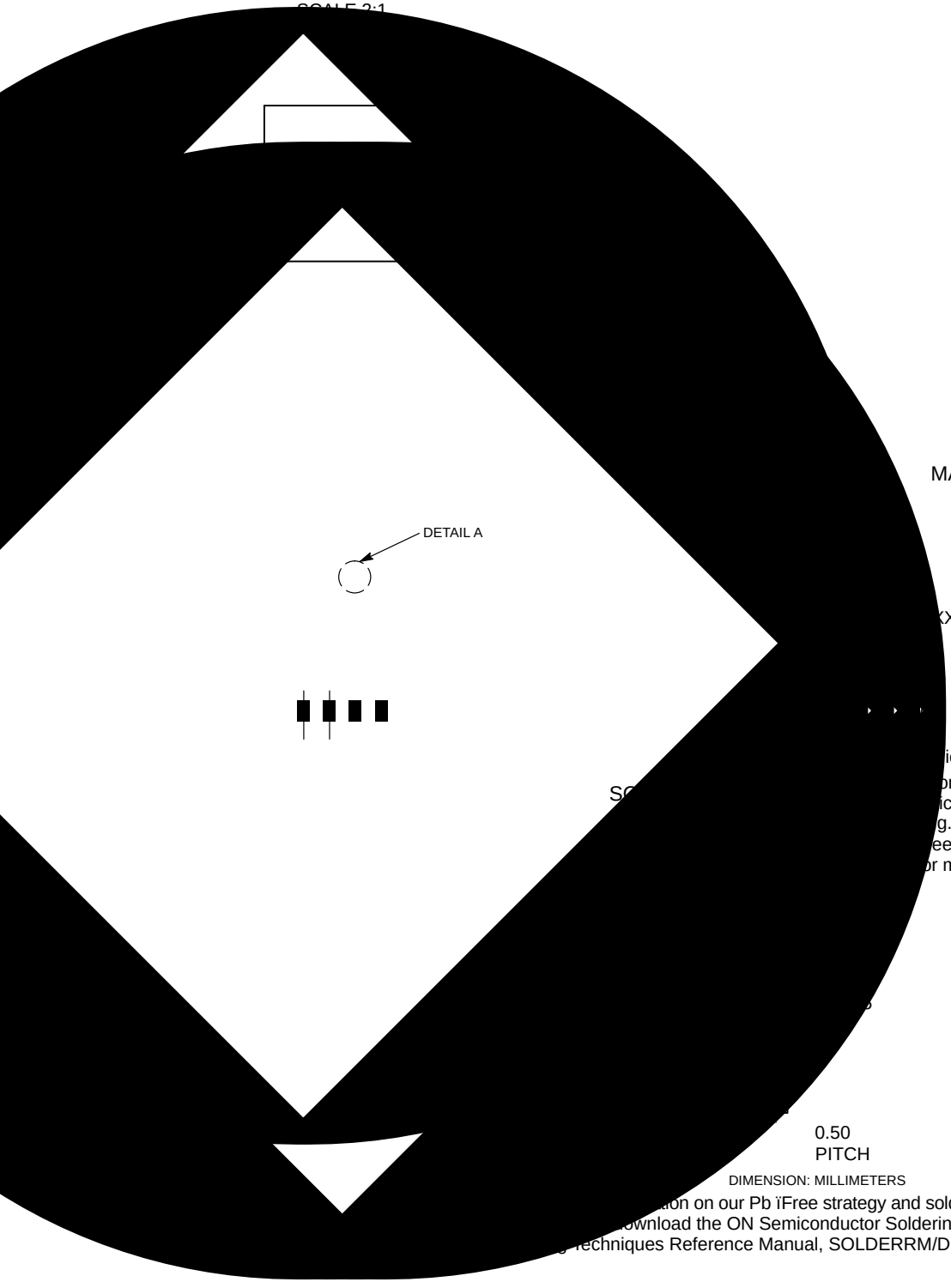
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

DFN8 3x3, 0.5P
CASE 506BJ ï01
ISSUE O

DATE 08 NOV 2007



GENERIC
MARKING DIAGRAM*

8

XXX = Specific Device Code
= Assembly Location
= Wafer Lot
= Year
= Work Week
= Pb ïFree Package

icrodot may be in either location)

ormation is generic. Please refer
ice data sheet for actual part
g.

ee indicator, “G” or microdot “ ”,
r may not be present.

0.50
PITCH

DIMENSION: MILLIMETERS

tion on our Pb ïFree strategy and soldering
ownload the ON Semiconductor Soldering and
Techniques Reference Manual, SOLDERRM/D.